



# DATA SHEET

SEMICONDUCTOR

YS2N3904

## TRANSISTOR (NPN)

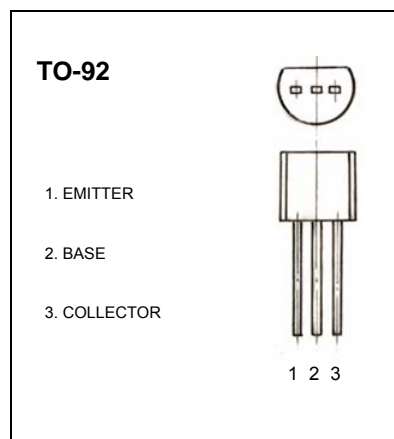


### FEATURE

- NPN silicon epitaxial planar transistor for switching and Amplifier applications
- As complementary type, the PNP transistor 2N3906 is Recommended
- This transistor is also available in the SOT-23 case with the type designation MMBT3904

### MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
$V_{CBO}$	Collector-Base Voltage	60	V
$V_{CEO}$	Collector-Emitter Voltage	40	V
$V_{EBO}$	Emitter-Base Voltage	6	V
$I_C$	Collector Current -Continuous	0.2	A
$P_C$	Collector Power Dissipation	0.625	W
$T_J$	Junction Temperature	150	$^{\circ}\text{C}$
$T_{stg}$	Storage Temperature	-55-150	$^{\circ}\text{C}$



### ELECTRICAL CHARACTERISTICS ( $T_{amb}=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C=10\mu\text{A}, I_E=0$	60			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	$I_C=1\text{mA}, I_B=0$	40			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E=10\mu\text{A}, I_C=0$	6			V
Collector cut-off current	$I_{CBO}$	$V_{CB}=60\text{V}, I_E=0$			0.1	$\mu\text{A}$
Collector cut-off current	$I_{CEO}$	$V_{CE}=40\text{V}, I_B=0$			0.1	$\mu\text{A}$
Emitter cut-off current	$I_{EBO}$	$V_{EB}=5\text{V}, I_C=0$			0.1	$\mu\text{A}$
DC current gain	$h_{FE1}$	$V_{CE}=1\text{V}, I_C=10\text{mA}$	100		400	
	$h_{FE2}$	$V_{CE}=1\text{V}, I_C=50\text{mA}$	60			
	$h_{FE3}$	$V_{CE}=1\text{V}, I_C=100\text{mA}$	30			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=50\text{mA}, I_B=5\text{mA}$			0.3	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C=50\text{mA}, I_B=5\text{mA}$			0.95	V
Transition frequency	$f_T$	$V_{CE}=20\text{V}, I_C=10\text{mA}, f=100\text{MHz}$	300			MHz
Delay Time	$t_d$	$V_{CC}=3\text{V}, V_{BE}=0.5\text{V}, I_C=10\text{mA}, I_{B1}=1\text{mA}$			35	ns
Rise Time	$t_r$				35	ns
Storage Time	$t_s$	$V_{CC}=3\text{V}, I_C=10\text{mA}$			200	ns
Fall Time	$t_f$	$I_{B1}=I_{B2}=1\text{mA}$			50	ns

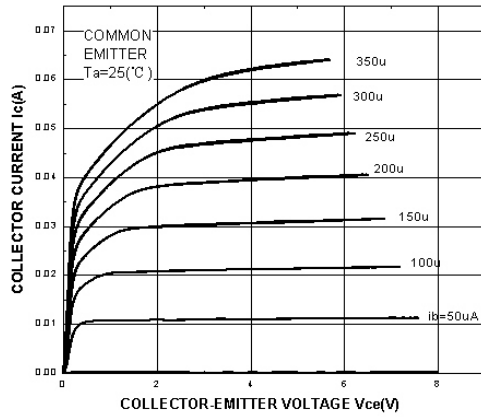
### CLASSIFICATION OF $h_{FE1}$

Rank	O	Y	G
Range	100-200	200-300	300-400

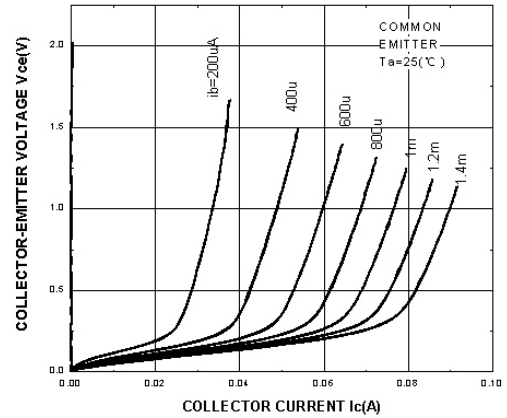
# DEVICE CHARACTERISTICS

YS2N3904

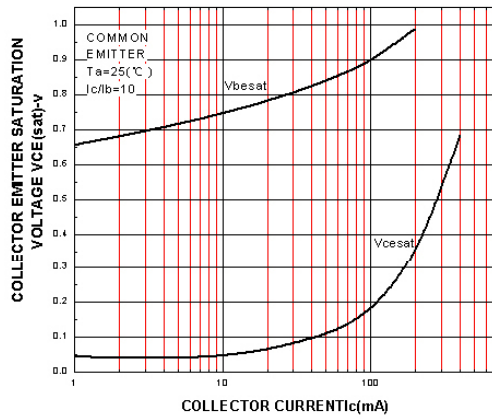
$I_c$ - $V_{ce}$



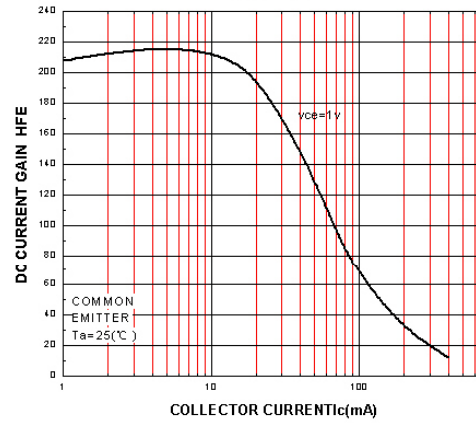
$V_{ce}$ - $I_c$



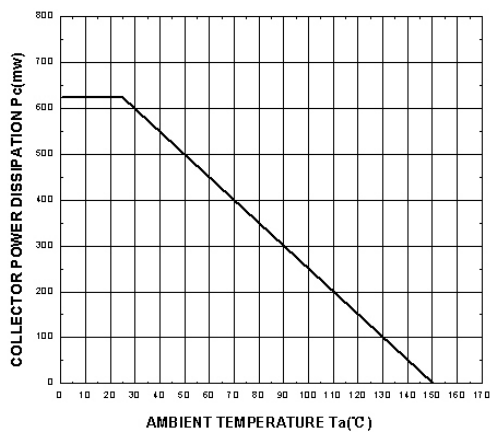
$V_{ce(sat)}$ - $I_c$   
 $V_{be(sat)}$ - $I_c$



$h_{FE}$ - $I_c$

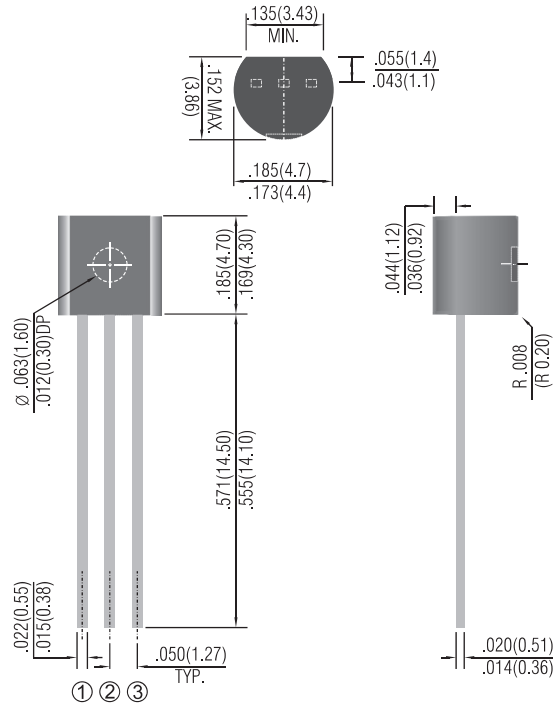


$P_c$ - $T_a$



# PACKAGE OUTLINE & DIMENSIONS

## YS2N3904

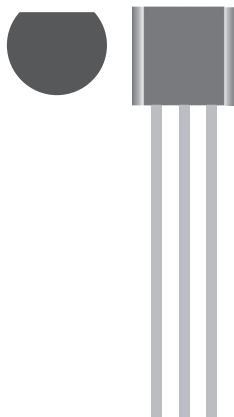




**亞昕科技股份有限公司**  
**Yea Shin Technology Co., Ltd.**

## TO-92 Marking Information

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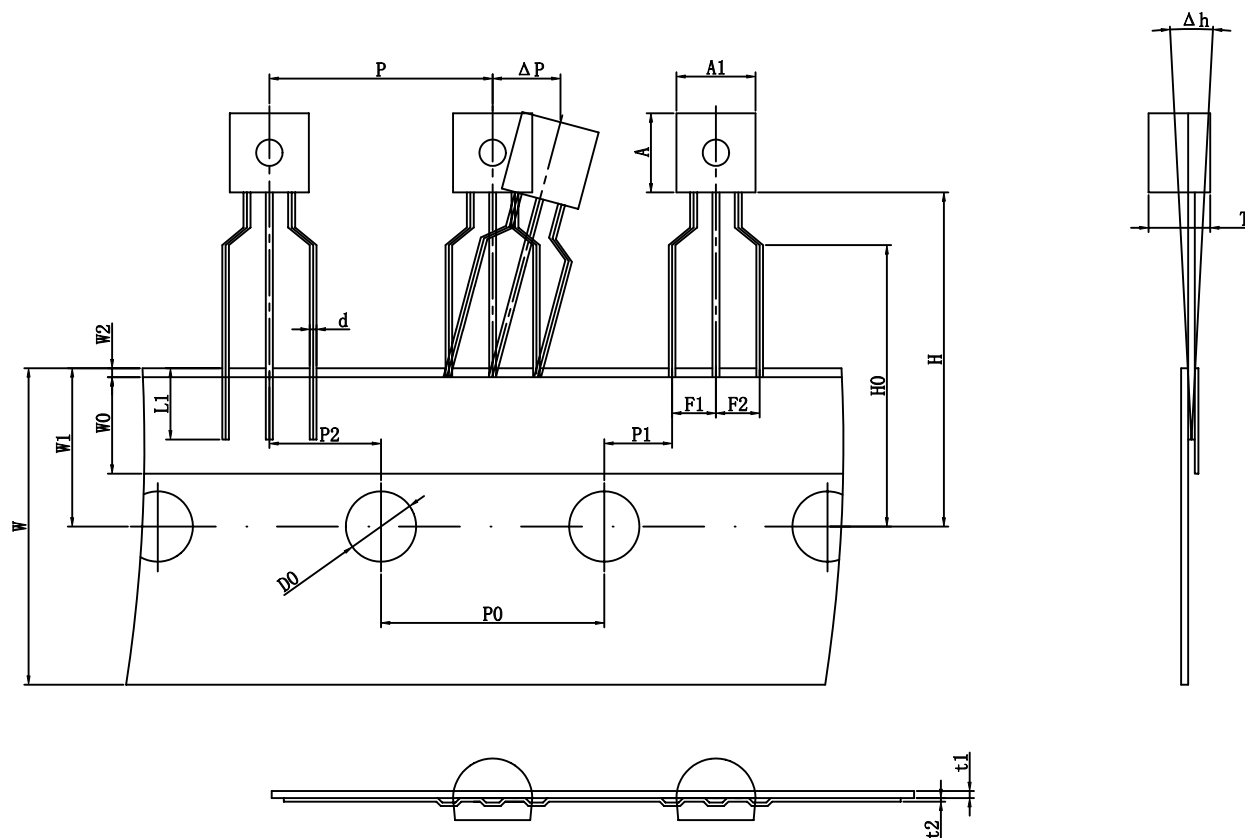
2N  
3904  
331

2N3904 : Device Code

331 : 產品識別碼



## TO-92 PACKAGE TAPEING DIMENSION



Item	Symbol	Value & Tolerance
Body width	A1	$4.5 \pm 0.1$
Body height	A	$4.5 \pm 0.1$
Body thickness	T	$3.5 \pm 0.1$
Lead wire diameter	d	$0.38 \pm 0.02$
Pitch of component	P	$12.7 \pm 0.3$
Feed hole pitch	P0	$12.7 \pm 0.2$
Hole center to component center	P2	$6.35 \pm 0.3$
Lead to lead distance	F1,F2	$2.5 \pm 0.3$
Component alignment, F-R	h	$0 \pm 1.0$
Type width	W	$18.0 + 1.0, - 0.5$
Hole down tape width	W0	$6.0 \pm 0.5$
Hole position	W1	$9.0 \pm 0.5$
Hole down tape position	W2	1.0 MAX
Height of component from tape center	H	$19.0 + 2.0, - 0$
Lead wire clinch height	H0	$16.0 \pm 0.5$
Lead wire(tape portion)	L1	2.5 MIN
Feed hole diameter	D0	$4.0 \pm 0.2$
Taped Lead Thickness	t1	$0.4 \pm 0.05$
Carrier Tape Thickness	t2	$0.2 \pm 0.05$
Position of hole	P1	$3.85 \pm 0.3$
Component alignment	P	$0 \pm 1.0$

Unit : mm